

Day 1: 29th Feb 2024						
Session	Moderator	Start	End	Start	End	Agenda
Registration		08:00	09:00	08:00	09:00	Registration of Participants
Welcome Dignitaries & Deep Prajwalan	Sh Ashok Chandak, President IESA	09:00	11:00	09:00	09:10	Prof Rao Tummala, Dr. Kamaljeet Singh (SCL), Sh. Ashok Chandak, Heads of India: Sh. Charan Gurumurthy (Tata), Sh. Hem Takiar (Micron), Smt. Jaya Jagdish (AMD), Sh. Vivek Sharma (STMicroelectronics), Sh. Ravi Bhatkal (MacDermid Alpha), Sh. Veerappan V (Tessolve),Sh. Navin Bishnoi (Marvell)
Welcome Address - Session Chair				09:10	09:20	Sh. Ashok Chandak, President IESA
Inaugural Addresses by Guest of Honours				09:20	10:20	Heads of India: Sh. Charan Gurumurthy (Tata), Sh. Hem Takiar (Micron), Smt. Jaya Jagdish (AMD), Sh. Vivek Sharma (STMicroelectronics), Sh. Ravi Bhatkal (MacDermid Alpha), Dr. Veerappan V (Tessolve),Sh. Navin Bishnoi (Marvell), Prof Rao Tummala, (G Tech, ISM), Dr. Kamaljeet Singh (SCL)
Inaugural Addresses by Chief Guest				10:20	10:45	Semiconductor & Packaging Vision, Strategy and Status: Honorable Chief Guest Sh. Rajeev Chandrasekhar, HMOS for Electronics and Information Technology and Skill Development & Entrepreneurship, Government of India
Sarabhai Award Presentation				10:45	10:50	Award Presentation by Ashok Chandak, IESA
Vote of Thanks				10:50	11:00	Closing Remarks
		11:00	11:40	11:00	11:30	Tea/Coffee Break & Exhibition Inaugration (Prof Rao Tummala, Dr Kamaljeet Singh, Sh Vikas Trikha,Dr Veerappan V
Plenary Session - Vision & Strategy for Semicon India	Sh Hem Takiar & Sh Charan Gurumurthy	11:30	13:00	11:30	12:10	Plenary Keynote 1: Can India be a Global Leader in Integrated Systems Packaging?: Prof. Rao Tummala, Advisor, Indian Semiconductor Mission (ISM), Founding Director and Emeritus Professor 3D Electronic Systems Packaging Research Center (PRC), Georgia Tech, Former IBM Fellow & Director of Adv. Packaging Lab, IBM
				12:20	12:40	Plenary Keynote 2: ISM - Indian Roadmap: Sh. Akash Tripathi, CEO, India Semiconductor Mission (ISM)
		13:00	14:00	13:00	14:00	Lunch Break
Industry Keynote Session - Global Products and Technologies	Sh Navin Bishnoi & Sh Manish Hooda	14:00	15:40	14:00	14:25	Keynote 1: Future of Computing and AI: Sh. Gokul Subramaniam, Intel
				14:25	14:50	Keynote 2: Future of Power Electronics: Sh. Charan Gurumurthy, TATA Semiconductor Assembly & Test
				14:50	15:15	Keynote 3: Future of Memory Devices & Package Integration w/ Logic: Sh. Hem Takiar, Micron
				15:15	15:40	Keynote 4: Future of 6G: Qualcomm, Sh Kapil Bhattad, Qualcomm
Academic Keynote Session - Strategic Technologies and Challenges	Prof. Abhijit Dasgupta, UMD & Prof. Abhisek Dixit, IITD	15:40	17:40	15:40	15:50	Overview of Global R&D Centers, Prof. Abhijit Dasgupta, UMD
				15:50	16:10	NCREPT & GRAPES - Research, Education and Industry Collaborations, University of Arkansas, USA, Prof. Alan Mantooh, U of Arkansas
				16:10	16:30	CHIMES - Research, Education and Industry Collaborations, Pennsylvania State University, USA, Prof. Madhavan Swaminathan, Penn State
				16:30	17:00	Tea/Coffee Break
				17:00	17:20	S3IP - Research, Education and Industry Collaborations, Binghamton University, USA Prof. Bahgat Sammikia and Dr. Srikanth Rangarajan, Binghamton University USA
				17:20	17:40	CALCE - Research, Education and Industry Collaborations, University of Maryland, USA, Prof. Abhijit Dasgupta, UMD
Director's Session	Prof. Rao Tummala & Prof. V. Ramgopal Rao	17:40	19:00	17:40	18:00	Georgia Tech Industry Consortium Model from Concept to Commercialization, Prof. Rao Tummala
				18:00	19:00	Panel Session: Heads of Indian Institutions: Director- IITH, IITJ, IITRPR, IITBBS, BITS-P, VC- MAHE
		19:30	21:30	19:30	21:30	Conference Dinner

Day 2: 1st Mar 2024						
Session	Moderator	Start	End	Start	End	Agenda
Large Scale, Next Gen, Global Level-R&D in India	Ravi Mahajan (Intel) & Prof. Rao Tummala (Georgia Tech)	08:30	16:20	08:30	08:50	Introduction to Large Scale, Global Level Next Gen R&D in Semiconductor's, Packaging and Systems: Prof. Rao Tummala
				08:50	09:20	System Design & Architectures: Prof. Binod Kumar (IITJ); Prof. Virendra Singh (IITB);
				09:20	09:50	Devices: Prof. Abhisek Dixit (IITD); Prof. Ankush Bag (IITG); Dr. Bijoy Krishna (IITM)
				09:50	10:20	Electronic Substrates: Prof. Pradeep Dixit (IITB) and Prof. Deepak Arora (IITJ)
				10:20	10:50	Tea/Coffee Break
				10:50	11:20	Thermal Management: Prof. A Bhattacharya (IITKGP), Prof. Amrit Ambirajan (IISc) and Prof. Somnath Roy (IITKGP)
				11:20	11:50	IC & Board Assembly and Reliability: Prof. Nilesh Badwe (IITK) and Prof. Shiv Govind Singh (IITH)
				11:50	12:20	6G Integrated Systems: Prof. MK Mandal (IITKGP); Prof. Siddhartha P Duttagupta (IITB); Prof. Gagan Kumar (IITG); Prof. Swaminathan (Penn State)
				12:20	12:50	Predictive Modeling & Design: Prof. T Agarwal (IITGN), Prof. Somnath Roy (IITKGP), Prof. Abhijit Dasgupta (Maryland);
				12:50	13:50	Lunch Break
				13:50	14:20	Integrated Sensors & MEMS: Prof. B Mitra (IITD); Prof. Venkatesh Rao (BITS Pilani)
				14:20	14:50	Power Electronics: Prof. Shiladri Chakraborty (IITB); Prof. Alan Mantooth (Arkansas)
				14:50	15:20	Co-Packaged Optics: Prof. N Emani (IITH); Prof. Sudharsanan Srinivasan (IITM)
				15:20	15:50	Materials - Devices and Packaging: Prof. B Prasad (IISc); Prof. Praveen Ramamurthy (IISc)
				15:50	16:20	System Level Electrical Test: Prof. J Tudu (IITTP) and Prof. Vasu Pulijalla (NIT Nagpur)
		16:20	16:50	16:20	16:50	Tea/Coffee Break
Consortium Discussion	Prof. Rao Tummala (Georgia Tech) & Ravi Mahajan (Intel)			16:50	17:30	Industry Consortium Discussion; Membership categories: R&D membership, WorkForce membership, Supply Chain Membership, Start up membership
Poster Session	Prof. Siddhartha Duttagupta (IITB) & Arun Chandrashekhar (Intel)			17:30	19:30	R&D Project Poster Presentations: Each company to review each poster and select R&D projects of interest
		18:00	19:30	18:00	19:30	Exhibitors' Reception

Day 3: 2nd Mar 2024						
Session	Moderator	Start	End	Start	End	Agenda
Workforce Development & Infrastructure Session	Ravi Bhatkal (MacDermid Alpha) & Amit Kachroo (Aark Global)	08:30	09:30	08:30	08:45	Education for Industry and Academic R&D: Needs and Proposed Programmes- Sh.Ravi Mahajan, Intel; Prof. Shiv Govind Singh, IITH
				08:45	09:00	Skills Development for Package Manufacturing Industry: Needs and Proposed Programmes- Sh. Gokul Kumar, Micron; Sh. Gagan Sain, Tata Electronics; Prof. Sid Duttgupta, IITB
				09:00	09:15	Infrastructure for R&D and education: Needs and proposed programmes- Sh. Ravi Bhatkal, MacDermid Alpha
				09:15	09:30	Role of Industry in Academic R&D programme- Prof. Nilesh Badwe, IITK
Global Supply Chain Session		09:30	09:45	09:30	09:45	Global Packaging Supply Chain Session Introduction: Sh. Kuldip Johal (USA) & Sh. Venky Sundaram (USA)
Materials & Chemicals Supply Chain	Venky Sundaram & Kuldip Johal	09:45	11:35	09:45	10:05	Packaging Materials & Package Solution Center Model: Sh. Hidenori Abe, Resonac (Japan) KEYNOTE
				10:05	10:15	Polymer Materials in Advanced IC Substrates: Sh. Habib Hichri , Ajinomoto (Japan)
				10:15	10:25	Process Chemicals and tools for advanced IC substrates: Sh. Naveen Goudar, MKS/Atotech (USA/India)
				10:25	10:35	Solder Resists and Dielectrics for Packaging: Sh. Meiten Koh, Taiyo Ink (Japan)
				10:35	11:05	Tea / Coffee Break
				11:05	11:15	Materials Solutions for Semiconductor Packaging, Substrates & Assembly: Sh. Ravi Bhatkal, MacDermid Alpha (USA/India)
				11:15	11:25	Materials for electronics assembly: Sh. Ram Trichur, Henkel (USA/India)
Wafer and Panel Equipment Supply Chain	Venky Sundaram & Kuldip Johal	11:35	13:00	11:25	11:35	Package Solutions and Assembly Materials: Sh. Takeshi Mori, Sumitomo Bakelite (Japan)
				11:35	11:55	Materials engineering solutions for Semiconductor/ Adv Packaging: Sh. Suraj Rengarajan, Applied Materials (USA/India) KEYNOTE
				11:55	12:15	Semiconductor precision processing tools: Sh.Takatoshi Kyo, President Disco (Japan/Singapore) KEYNOTE
				12:15	12:25	Thin Film Advanced Technology: Sh.Suresh Singaram, Evatec (India/Switzerland)
				12:25	12:35	Total solution for package Assembly: Sh. Nelson Wong, K&S (Singapore)
				12:35	12:45	Semiconductor Assembly Equipment: Sh. Chin Seng Chu, BESI (Netherlands/Singapore)
		12:45	12:55	12:45	12:55	Factory Automation: Sh. Peter Chew, Yamaha Robotics (Japan)
		13:00	14:00	13:00	14:00	Lunch Break
Design, Substrates, Wafer-Level Packages, Assembly and Test	Venky Sundaram & Kuldip Johal	14:00	15:20	14:00	14:20	Global Status of Memory Substrates and Plans for India : Sh. Ken Lee, Simmtech (Korea) KEYNOTE
				14:20	14:30	Ceramic Substrates for Semiconductor Packaging: Sh. Tatsuya Okabe, Kyocera (Japan/India)
				14:30	14:40	Organic Substrate Manufacturing: Sh. Ibrath Ha, AT&S (Austria/India)
				14:40	14:50	Assembly Test & Packaging, Sh. Raghu Panicker, Kaynes (India)
				14:50	15:00	Virtualisation of Chip-Package Co design for Shift Left in product development: Sh. Shital Joshi, Ansys (USA/India)
				15:00	15:10	Integrated approach for investigating advanced package failure through correlative X-ray Microscopy and Laser Focused Ion Beam (FIB) Techniques: Sh. Arun Prabha, Carl Zeiss, (Germany/India)
		15:10	15:20	15:10	15:20	Metrology & Instruments in Semiconductor & Packaging: Sh. Olivier Dulac, Ametek (France)
Summary	Prof. Rao Tummala			15:20	15:30	ISPEC2024 Summary & Closing Remarks: Prof Rao Tummala
		15:30	16:00	15:30	16:00	Tea / Coffee Break
SCL Facility Tour	Gurvinder Singh & SCL Team	16:00	17:30	16:00	17:30	SCL Facility Tour: Sh Gurvinder Singh & SCL team